

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCI No.	MDG/22/13768
1.3 Title of PCI	ST MUAR Enhanced traceability with 2D marking for LQFP7x7, LQFP10x10 & LQFP14x14 additional products
1.4 Product Category	All listed products
1.5 Issue date	2022-12-13

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.2.2 Marketing Manager	Veronique BARLATIER
2.2.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Traceability (marking content, company logo, etc)	ST Muar (Malaysia)

4. Description of change

	Old	New
4.1 Description	Marking composition with no 2D marking	New marking composition with 2D marking for production assembly
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form: Change is visible on marking area Fit : No change Function : No change Reliability : No change Processability : No change	

5. Reason / motivation for change

5.1 Motivation	to enhance traceability
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	2D marking visible on top device marking
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7. Timing / schedule

7.1 Date of qualification results	2022-11-09
7.2 Intended start of delivery	2022-12-09
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	
8.2 Qualification report and qualification results	In progress

9. Attachments (additional documentations)

13768 Public product.pdf
13768 PCI13768_Additional information.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F091RCT6J	
	STM32F100RCT6	
	STM32F100RCT6TR	
	STM32F100VCT6	
	STM32F100VDT6	
	STM32F100VET6	
	STM32F105RCT6V	
	STM32F105VCT6V	
	STM32F105VCT6W	
	STM32F205VGT6V	
	STM32F205VGT6W	
	STM32F405VGT6V	
	STM32F405VGT6W	
	STM32F407VGT6J	

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PRODUCT/PROCESS CHANGE INFORMATION

PCI13768 – Additional information

ST MUAR Enhanced traceability with 2D marking for LQFP7x7, LQFP10x10 & LQFP14x14 additional products

MDG – General Purpose Microcontrollers sub-group (GPM)

What is the change?

Purpose is to homogenize the marking composition to allow better identification of STM8/STM32 products whatever the production site (for package bigger or equal to 7x7mm body size).

For all listed products marking composition will include 2D information. This enhanced traceability will allow a unique traceability per device from manufacturing to the end customer.

Codes already available on current marking:

PP : Assembly Plant code

LLL : BE sequence

WX : Wafer Diffusion Plant code

SS : ASsembly Sub-Lot

COO : Country Of Origin code

TF : Test & Finishing site code

Y WW : Year Week (manufacturing date)

R : Additional Information (Die Version)

Impacted Assembly site	COO Country Of Origin	PP Product Plant
ST Muar (Malaysia)	MYS	99

How can the change be seen?

Table below shows marking examples for different package.

Impacted Package	Current marking composition example	New marking composition example
	Without	With 2D Marking
LQFP 32 7x7x1.4 MM	<p>STM8S207 K8T6C PP LLL WX COO Y WW SS ●  (e3) R</p>	<p> (e3) 2D STM8S207 K8T6C PP LLL WX R ● COO Y WW SS</p>
LQFP 48 7x7x1.4 MM	<p>32F100 C8T6B PP LLL SS WX COO TF Y WW ●  (e3) R</p>	<p> (e3) 2D STM32F100C8T6B PP LLL WX R ● COO Y WW SS</p>
LQFP 64 10x10x1.4 MM	<p>Logo R STM32F101 RCT6 PP LLL WX COO TF Y WW  (e3) SS</p>	<p> (e3) STM32F101R CT6 PP LLL WX R COO TF Y WW ● SS</p>
LQFP 100 14x14x1.4 MM	<p>STM32F071 VBT6 PP LLL WX COO TF Y WW R  (e3) Logo SS</p>	<p> (e3) 2D STM32F071VB T6 PP LLL WX R COO TF Y WW ● SS</p>

Some specific highlights:

- New marking will replace current marking.
- To save some space, “TF” code information has been removed from LQFP48 marking.
- Marking area is broken out into two separate lines to allow maximum information to be displayed.
 - o In the new marking condition, the marking area (lines in blue color in above table) will be filled up to the last possible character of the first line and will be resumed on the second line.
- As a consequence, the cardboard box labeling will also display this change, but we may have mismatch between Box Labelling and marking composition of parts inside this box during the transition time for about a few weeks. Refer to below examples of box labeling.

Package size with box labeling examples	Box labeling before:	Box labeling after:
LQFP 32 7x7x1.4 MM	STM8S207 K8T6C V	STM8S20 7K8T6C V
LQFP 48 7x7x1.4 MM	32F100 C8T6B Z	STM32F1 00C8T6B Z
LQFP 64 10x10x1.4 MM	STM32F101 RCT6 2	STM32F101R CT6 2
LQFP 100 14x14x1.4 MM	STM32F071 VBT6 Y	STM32F071VBT 6 Y



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Public Products List

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PCI Title : ST MUAR Enhanced traceability with 2D marking for LQFP7x7, LQFP10x10 & LQFP14x14 additional products

PCI Reference : MDG/22/13768

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F207VGT6J	STM32F405VGT6W	STM32F100VET6
STM32F205VGT6J	STM32F105VCT6W	STM32F205VGT6W
STM32F100VDT6	STM32F205VGT6V	STM32F105VCT6V
STM32F100RCT6TR	STM32F405VGT6J	STM32F105RCT6V
STM32F100RCT6	STM32F407VGT6J	STM32F405VGT6V
STM32F105RCT6W	STM32F100VCT6	STM32F091RCT6J
STM32F103VGT6J		

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